

Quick Reference

Search by part #

Check distributor part inventory

Products

Browse Heat sinks

-By Device -

-By Product Line -

-Attachment Methods -

-Interface Materials -

-Accessories -

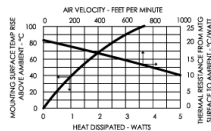
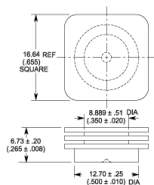
Useful Links

- [Building a part #](#)
- [Catalog Request](#)
- [Directions](#)
- [Find Distributor](#)
- [Find Sales Rep](#)
- [How to order?](#)
- [MSDS Safety Sheets](#)
- [Part # Cross Ref](#)
- [Quote Request](#)
- [RoHS Initiative](#)
- [Sample Request](#)

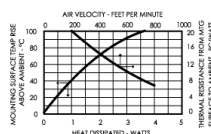
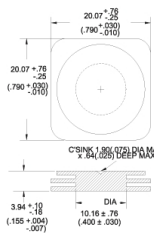
Products / BGA / Radial Fins
Radial Fin Heat Sinks for Microprocessors

- Bond-on heat sinks for leadless chip carriers and flat packs.
- Primarily designed for 68-position devices.
- The 2283 is ideally suited to limited board space applications with high air flow.

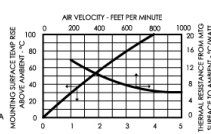
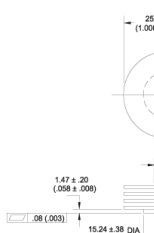
Part Number: 2283BG



Part Number: 2286BG

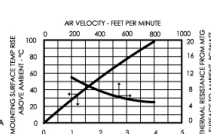
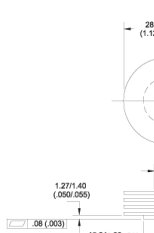


Part Number: 2288BG



Part Number: 2292BG

RoHS Compliant



Part Number: 2296BG

